ABSOCIATION CONNECTING LECTRONICS INDUSTRIES INCOMPACTING	IPC. Bannock	burn. Illinois. A	Il rights reserved un ntions.	nder both	This docum level parts, t	ent is a declaration en	n of the substat compasses all l	nces within the manufactu ower level materials for v	rer listed	item. Note: if manufacturer	the item is an as has engineering	sembly with lower responsibility.	
				Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information				on				
Supplier Information													
Company name* Company			unique ID			Unique ID Authority				Response Date*			
onsemi										2024-04-16			
Contact Name Title - Contact			tact			Phone - Contact*			Email	Email - Contact*			
Product-Env-Stewards Product Envi			viro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repres			esentative			Phone - Representative*			Email	Email - Representative*			
Product-Env-Stewards Product E			uct Enviro Compliance			NA			Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	er Mfr Item Number		Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	S2M	S2M SR SMB GPPN 1.		.5A 1000V		2024-04-16 TSCBE		TSCBE		90.0004	mg	Each	
Manufacturing Proccess Informa	ition												
Terminal Plating / Grid Array Material Terminal Base All		Alloy J	-STD-020 MSL	Rating	Peak Proces	ss Body Tempe	rature Max Time at Peak	. Tempera	ature Numbe	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	seco	nds 3				
Comments													
evel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds										
or more information regarding materia	composition	please refer to	page 3										

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part, the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select	the Level (JIG A, JIG B	, Requester or Supplier) [B] select the substa	ance category (JIG or Requester) or enter a	value (Supplier). [C] selec	ct the substance (JI	G) or enter the substa	nce and CAS (Other). [D]
select a RoHS exemption, if applied sigma range of distribution unless	cable [E] enter the weigh otherwise noted).	nt of the substance or the P	PM concentration	[F] Optionally enter the positive (+) and n	egative (-) tolerance in per	cent (Note: percer	t tolerance values are	expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	10.667	mg	Supplier	Copper (Cu)	7440-50-8		10.667	mg
Die	1.2132	mg	Supplier	Silicon (Si)	7440-21-3		1.0919	mg
			В	Nickel (Ni)	7440-02-0		0.0079	mg
			Supplier	Gold (Au)	7440-57-5		0.0018	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.1116	mg
Die Attach Solder	2.3616	mg	Supplier	Silver (Ag)	7440-22-4		0.059	mg
			А	Lead (Pb)	7439-92-1	7a	2.1845	mg
			Supplier	Tin (Sn)	7440-31-5		0.1181	mg
Lead Frame	26.802	mg	Supplier	Iron (Fe)	7439-89-6		0.0322	mg
			Supplier	Copper (Cu)	7440-50-8		26.7618	mg
			Supplier	Phosphorus (P)	7723-14-0		0.008	mg
Mold Compound-Black	48.755	mg		Metal Hydroxide	proprietary data		1.7064	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.9004	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2438	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.004	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.9004	mg
Plating	0.2016	mg	Supplier	Tin (Sn)	7440-31-5		0.2016	mg